

Microbond Tacky Flux



NC5070

No clean, tacky flux for bumping, BGA and CSP, surface mount and hybrid applications.

- Suited for leadfree and lead containing bumps
- Excellent wetting behavior
- Perfect cleaning properties
- Blue or amber color available

Composition

Meets IPC J-STD-004A: requirements for soldering flux

Flux classification: ROL0

Halogen free

Storage and Handling

Shelf life in original, unopened packing: 12 months at 20 to 25°C

- Optimum storage conditions: fridge at 5 to 10°C
- No direct sunlight
- Relative humidity < 80%

Properties

Flux type ¹ :	ROL0
pH value:	4.7 - 4.9
Halide content ¹ :	halide free
Copper mirror test ¹ :	no breakthrough
SIR test ¹ :	pass
Viscosity range ² :	150 - 450 kcps
Tackiness:	> 100 gf
Fineness of grind:	< 30 µm

1 IPC J-STD-004A (IPC-TM-650)

2 Brookfield RVT, spindle TE, 5 rpm, 23°C

Additional Information

Microbond tacky fluxes are suited for pin transfer, printing or ball dipping application techniques. Microbond tacky fluxes are compliant with the RoHS and ELV regulations.

Reflow Characteristics and Recommendations

NC5070 fluxes are compatible with automated flux application methods or for manual flux application.

Prior to use, allow the cartridges to reach room temperature (minimum 2h) before opening.

A few sweeping moves of the squeegee on the flux reservoir are recommended. Optimal results can be obtained by cleaning the flux reservoir every 8h.

NC5070 fluxes are compatible with convection or infrared reflow techniques.

Recommended peak temperature for eutectic Pb-containing solder bumps is 195 to 220°C and 20 to 60 seconds above melting point for standard applications.

Recommended peak temperature for Pb-free solder bumps is 240 to 260°C and 20 to 60 seconds above melting point for standard applications

Packaging

The NC5070 series of Microbond tacky fluxes are available in convenient ready-to-use cartridges.

Standard cartridge packages are 6 oz and 150 g.

Other packages may be available on request.

Quality Assurance

Each lot of flux product is manufactured under controlled conditions to ensure a stable and high quality.

Manufacturing, packing and quality control are performed in accordance with ISO/TS16949.

The manufacturing process is compliant with the requirements of ISO14001.

Safety

When handling solder paste, always observe good industrial hygiene and safe working practices.

Avoid contact with skin and eyes.

Consult the Materials Safety Data Sheet before use.

Rev. 0 – June 2009

Germany
W.C. Heraeus GmbH

Phone: +49 6181 35-5703
e-mail: stefan.merlau@heraeus.com

Indian Distributor :
Mectronics Marketing Services
(AN ISO 9001:2008 CERTIFIED COMPANY)
New Delhi, India
Tel: +91 (011) 42208256 / 43041581
Email : mectronics@mectronics.in
Web: www.mectronics.in

Singapore
Heraeus Materials Singapore Pte Ltd

Phone: +65 65717 684
e-mail: alexander.brand@heraeus.com